# MURD340T4G, NRVUD340T4G

# **SWITCHMODE Power Rectifier**

# **DPAK Surface Mount Package**

These state-of-the-art devices are designed for use in switching power supplies, inverters and as free wheeling diodes.

#### **Features**

- Low Forward Voltage Drop
- Low Leakage
- Ultra-Fast Recovery Time
- AEC-Q101 Qualified and PPAP Capable
- NRVUD Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- Pb–Free Package\*

### **Mechanical Characteristics**

- Case: Epoxy, Molded
- Weight: 0.4 gram (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds

## **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Reverse Voltage	V <sub>R</sub>	400	V
Average Rectified Forward Current	I <sub>F(AV)</sub>	3	Α
Nonrepetitive Peak Surge Current	I <sub>FSM</sub>	75	Α
Operating Junction and Storage Temperature Range	T <sub>J,</sub> T <sub>stg</sub>	-55 to +175	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.



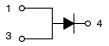
# ON Semiconductor®

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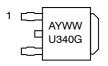
# ULTRAFAST RECTIFIER 3 A, 400 V



**DPAK CASE 369C** 



#### MARKING DIAGRAM



U340 = Specific Device Code = Assembly Location Α

٧ = Year ww = Work Week = Pb-Free Package

## ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MURD340T4G	DPAK (Pb-Free)	2,500 / Tape & Reel
NRVUD340T4G	DPAK (Pb-Free)	2,500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# MURD340T4G, NRVUD340T4G

# THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance – Junction-to-Case	$R_{ heta JC}$	2	°C/W
Thermal Resistance – Junction–to–Ambient (Note 1)	$R_{\theta JA}$	49	°C/W

<sup>1.</sup> Rating applies when surface mounted on a 700  $\,\mathrm{mm^2}$ , 1 oz Cu heat spreader.

# **ELECTRICAL CHARACTERISTICS**

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage ( $I_F = 3.0 \text{ A}, T_J = 25^{\circ}\text{C}$ ) ( $I_F = 3.0 \text{ A}, T_J = 150^{\circ}\text{C}$ )	V <sub>F</sub>	1.15 0.92	V
Maximum Instantaneous Reverse Current (Rated $V_R$ ) (T <sub>J</sub> = 25°C, 400 V) (T <sub>J</sub> = 150°C, 400 V)	I <sub>R</sub>	5 500	μΑ
Maximum Reverse Recovery Time (I <sub>F</sub> = 1.0 A, di/dt = 50 A/ $\mu$ s, V <sub>R</sub> = 30 V, T <sub>J</sub> = 25°C)	t <sub>rr</sub>	50	ns
ESD Ratings:  Machine Model = C  Human Body Model = 3B		> 400 > 8000	V

# **TYPICAL CHARACTERISTICS**

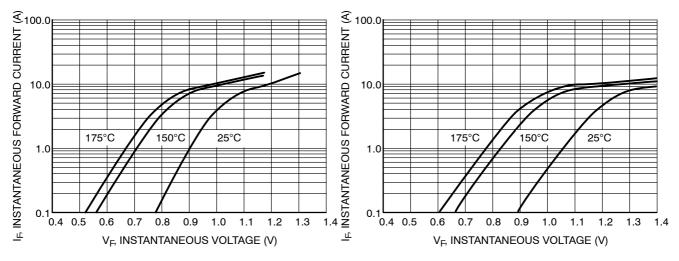


Figure 1. Typical Forward Voltage

Figure 2. Maximum Forward Voltage

# MURD340T4G, NRVUD340T4G

## **TYPICAL CHARACTERISTICS**

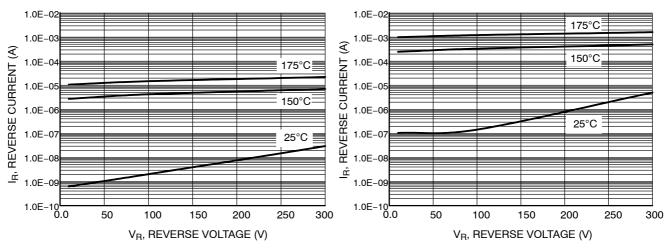


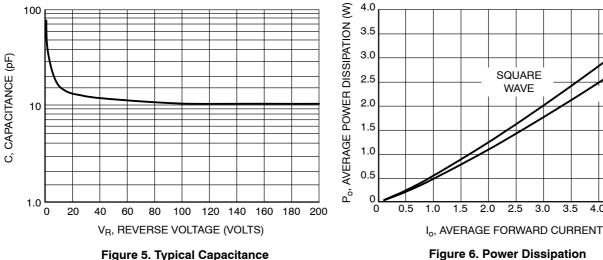
Figure 3. Typical Reverse Voltage

Figure 4. Maximum Reverse Voltage

DC

4.0

4.5



DC

170

SQUARE WAVE

Figure 5. Typical Capacitance

6.0

5.0

4.0

3.0

2.0

1.0

100

110

 $R_{\theta JC} = 2^{\circ}C/W$ 

 $T_J = 175^{\circ}C/W$ 

IF, AVERAGE FORWARD CURRENT (A)

6.0 I<sub>F</sub> AVERAGE FORWARD CURRENT (A)  $R_{\theta JC} = 2^{\circ}C/W$ 5.0  $T_{.1} = 175^{\circ}C/W$ 4.0 DC 3.0 SQUARE 2.0 WAVE 1.0 0 180 20 100 120 160 180 200 0 80 TA, AMBIENT TEMPERATURE (°C)

T<sub>C</sub>, CASE TEMPERATURE (°C) Figure 7. Current Derating, Case

140

150

130

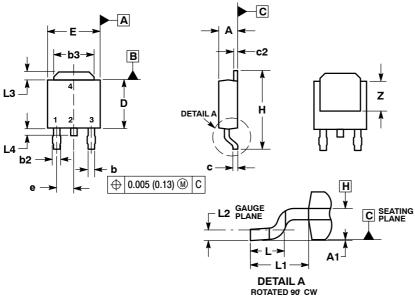
Figure 8. Current Derating, Ambient

# MURD340T4G, NRVUD340T4G

#### PACKAGE DIMENSIONS

# **DPAK (SINGLE GAUGE)**

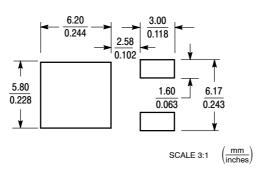
CASE 369C-01 ISSUE D



- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994
- 2. CONTROLLING DIMENSION: INCHES.
  3. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-
- MENSIONS b3, L3 and Z.
  4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
  5. DIMENSIONS D AND E ARE DETERMINED AT THE
- OUTERMOST EXTREMES OF THE PLASTIC BODY.
- 6. DATUMS A AND B ARE DETERMINED AT DATUM

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.086	0.094	2.18	2.38
<b>A</b> 1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.030	0.045	0.76	1.14
b3	0.180	0.215	4.57	5.46
С	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
Е	0.250	0.265	6.35	6.73
е	0.090 BSC		2.29 BSC	
Н	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.108 REF		2.74 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4		0.040		1.01
Z	0.155		3.93	

### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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